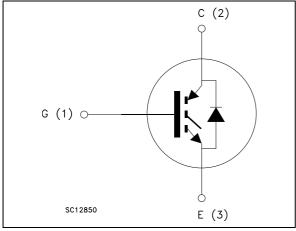


# STGW40NC60KD

## 600 V, 40 A short-circuit rugged IGBT

# TO-247

#### Figure 1. Internal schematic diagram



#### Datasheet - production data

### **Features**

- Low on-voltage drop (V<sub>CE(sat)</sub>)
- Low C<sub>res</sub> / C<sub>ies</sub> ratio (no cross conduction susceptibility)
- Short-circuit withstand time 10 µs
- IGBT co-packaged with ultra fast free-wheeling diode

## **Applications**

- High frequency inverters
- Motor drivers

## Description

This IGBT utilizes the advanced PowerMESH<sup>™</sup> process resulting in an excellent trade-off between switching performance and low on-state behavior.

#### Table 1. Device summary

Order code	Marking	Package	Packaging
STGW40NC60KD	GW40NC60KD	TO-247	Tube

This is information on a product in full production.

## Contents

1	Electrical ratings	3
2	Electrical characteristics	1
	2.1 Electrical characteristics (curves)	3
3	Test circuits	J
4	Package mechanical data 10	)
5	Revision history	2





## 1 Electrical ratings

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage (V <sub>GE</sub> = 0)	600	V
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at T <sub>C</sub> = 25 °C	70	А
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at T <sub>C</sub> = 100 °C	38	А
I <sub>CL</sub> <sup>(2)</sup>	Turn-off latching current	220	А
I <sub>CP</sub> <sup>(3)</sup>	Pulsed collector current	220	А
V <sub>GE</sub>	Gate-emitter voltage	±20	V
١ <sub>F</sub>	Diode RMS forward current at $T_{C} = 25 \text{ °C}$	30	Α
I <sub>FSM</sub>	Surge non repetitive forward current t <sub>p</sub> = 10 ms sinusoidal	120	А
P <sub>TOT</sub>	Total dissipation at $T_{C}$ = 25 °C	250	W
t <sub>scw</sub>	Short circuit withstand time, $V_{CE} = 0.5 V_{(BR)CES}$ T <sub>j</sub> = 125°C, R <sub>G</sub> = 10 Ω, V <sub>GE</sub> = 12 V	10	μs
Тj	Operating junction temperature	– 55 to 150	°C

1. Calculated according to the iterative formula:

$$I_{c}(T_{c}) = \frac{T_{J(MAX)} - T_{c}}{R_{thj-c} \times V_{CE(sat)(MAX)} \cdot (T_{c},I_{c})}$$

2.  $V_{clamp} = 80\%, (V_{CES}), T_j = 150^{\circ}C, R_G = 10 \Omega, V_{GE} = 15 V$ 

3. Pulse width limited by max. junction temperature allowed

Table 3.	Thermal	resistance
----------	---------	------------

Symbol	Parameter	Value	Unit
D	Thermal resistance junction-case IGBT max.	0.5	°C/W
R <sub>thj-case</sub>	Thermal resistance junction-case diode max.	1.5	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient max	50	°C/W



## 2 Electrical characteristics

 $T_{CASE}$ =25°C unless otherwise specified.

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)CES</sub>	Collector-emitter breakdown voltage ( $V_{GE}$ = 0)	I <sub>C</sub> = 1 mA	600			V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_{C} = 30 \text{ A}$ $V_{GE} = 15 \text{ V}, I_{C} = 30 \text{ A},$ $T_{C} = 125 \text{ °C}$		2.1 1.9	2.7	V V
I <sub>CES</sub>	Collector cut-off current $(V_{GE} = 0)$	V <sub>CE</sub> = 600 V V <sub>CE</sub> = 600 V, T <sub>C</sub> = 125 °C			500 5	μA mA
V <sub>GE(th)</sub>	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 250 \ \mu A$	4.5		6.5	V
I <sub>GES</sub>	Gate-emitter cut-off current (V <sub>CE</sub> = 0)	V <sub>GE</sub> = ±20 V			±100	nA
9 <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	$V_{CE} = 15 \text{ V}, I_{C} = 30 \text{ A}$		20		S

Table 4. Static

1. Pulsed: Pulse duration =  $300 \ \mu$ s, duty cycle 1.5%

Table	5.	Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>CE</sub> = 25 V, f = 1 MHz, V <sub>GE</sub> = 0	-	2870 295 69	-	pF pF pF
Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>	Total gate charge Gate-emitter charge Gate-collector charge	V <sub>CE</sub> = 480 V, I <sub>C</sub> = 30 A, V <sub>GE</sub> = 15 V (see Figure 18)	-	135 27 69.5	-	nC nC nC

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ (see Figure 17)	-	46 18.5 1530	-	ns ns A/µs
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ $T_C = 125 \text{ °C} (see Figure 17)$	-	45 19 1400	-	ns ns A/µs
t <sub>r(Voff)</sub> t <sub>d(off)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ (see Figure 17)	-	38 164 87	-	ns ns ns
t <sub>r(Voff)</sub> t <sub>d(off)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{cc} = 480 \text{ V}, I_{C} = 30 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$ $T_{C} = 125 \text{ °C}$ <i>(see Figure 17)</i>	-	70 208 130	-	ns ns ns

Table 6. Switching on/off (inductive load)

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E <sub>on</sub> E <sub>off</sub> <sup>(1)</sup> E <sub>ts</sub>	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ (see Figure 17)	-	595 716 1311	-	μJ μJ
E <sub>on</sub> E <sub>off</sub> <sup>(1)</sup> E <sub>ts</sub>	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}, I_C = 30 \text{ A}$ $R_G = 10 \Omega, V_{GE} = 15 \text{ V},$ $T_C = 125 \text{ °C}$ <i>(see Figure 17)</i>	-	808 1200 2008	-	μJ μJ

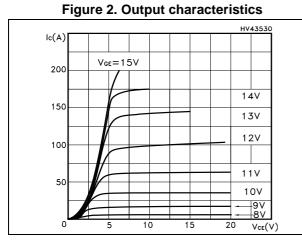
1. Turn-off losses include also the tail of the collector current.

#### Table 8. Collector-emitter diode

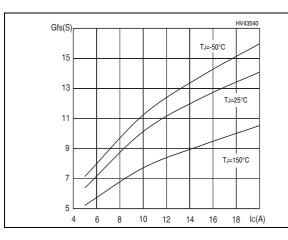
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>F</sub>	Forward on-voltage	I <sub>F</sub> = 30 A I <sub>F</sub> = 30 A, T <sub>C</sub> = 125 °C	-	2.4 1.8	-	V V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 30 \text{ A}, V_R = 50 \text{ V},$ di/dt = 100 A/ $\mu$ s (see Figure 20)	-	45 56 2.55	-	ns nC A
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 30 \text{ A}, V_R = 50 \text{ V},$ $T_C = 125 \text{ °C}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$ (see Figure 20)	-	100 290 5.8	-	ns nC A

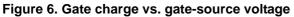


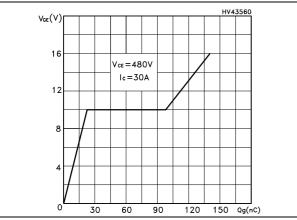
## 2.1 Electrical characteristics (curves)



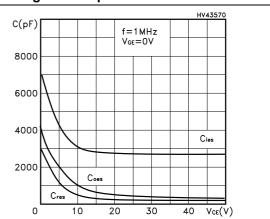
#### Figure 4. Transconductance







#### Figure 7. Capacitance variations



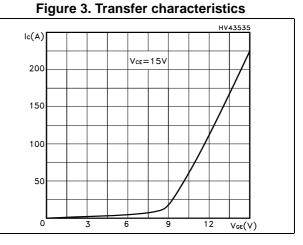


Figure 5. Collector-emitter on voltage vs. temperature

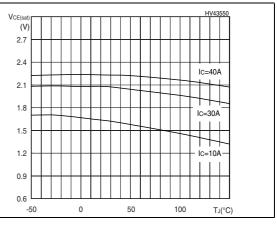


Figure 8. Normalized gate threshold voltage vs. temperature

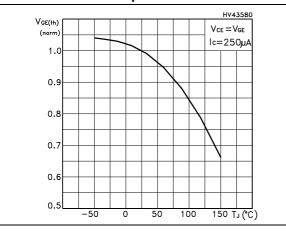


Figure 10. Normalized breakdown voltage vs. temperature

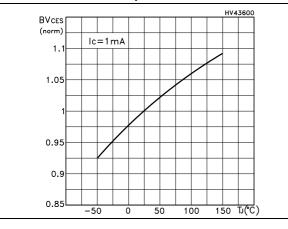


Figure 12. Switching losses vs. gate resistance

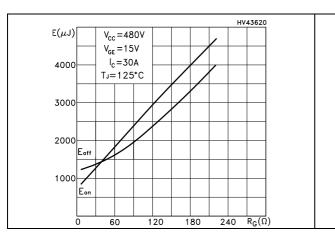


Figure 9. Collector-emitter on voltage vs. collector current

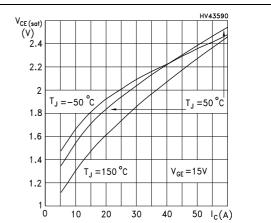


Figure 11. Switching losses vs. temperature

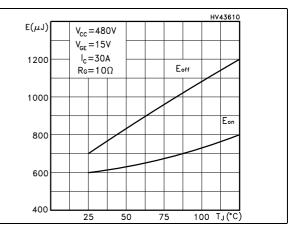


Figure 13. Switching losses vs. collector current

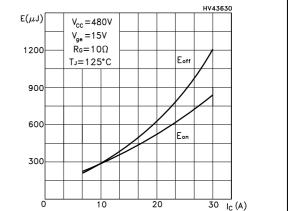




Figure 14. Thermal Impedance

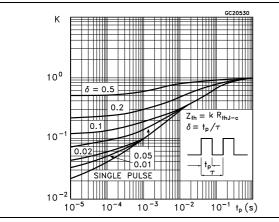


Figure 16. Forward voltage drop vs. forward current

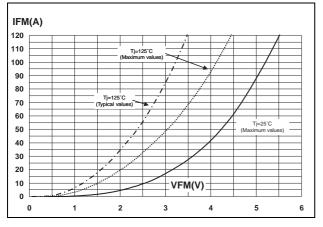
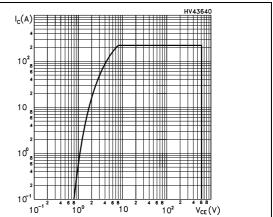
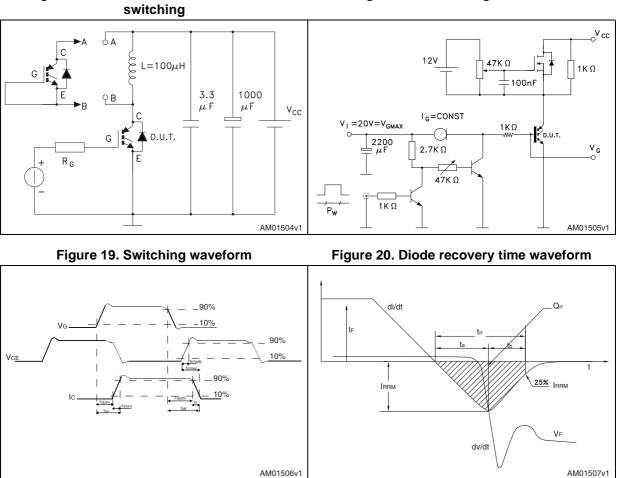


Figure 15. Turn-off SOA



## 3 Test circuits



# Figure 17. Test circuit for inductive load switching

Figure 18. Gate charge test circuit



#### Package mechanical data 4

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.

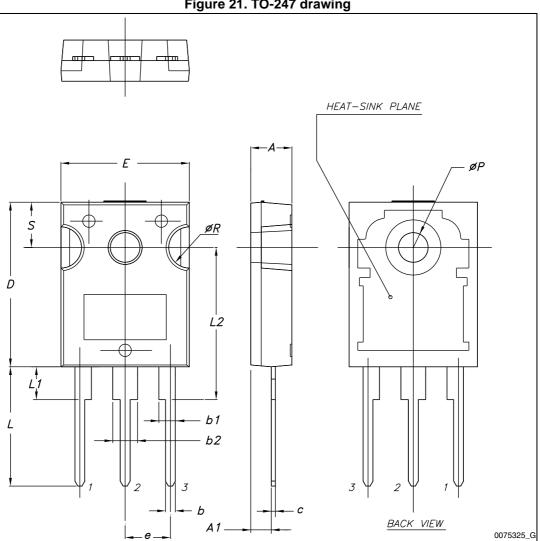


Figure 21. TO-247 drawing



Dim. —	mm.			
	Min.	Тур.	Max.	
А	4.85		5.15	
A1	2.20		2.60	
b	1.0		1.40	
b1	2.0		2.40	
b2	3.0		3.40	
С	0.40		0.80	
D	19.85		20.15	
E	15.45		15.75	
е	5.30	5.45	5.60	
L	14.20		14.80	
L1	3.70		4.30	
L2		18.50		
ØP	3.55		3.65	
ØR	4.50		5.50	
S	5.30	5.50	5.70	

Table 9. TO-247 mechanical data



## 5 Revision history

Date	Revision	Changes	
11-Jun-2008	1	Initial release	
12-Mar-2014	2	Modified total switching losses typical value in <i>Table 7:</i> <i>Switching energy (inductive load)</i> . Minor text changes.	

Table 10. Document revision history



#### Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries. Information in this document supersedes and replaces all information previously supplied. The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2014 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com



DocID14807 Rev 2